

TECHNICAL DATA SHEET

Thermal conductive paste Carbon

Advanced thermal paste with carbon nanoparticles sets a new standard in electronics cooling. With an impressive thermal conductivity of 15.2 W/mK, it effectively and rapidly dissipates heat from processors, GPUs, and other high-temperature components. Its innovative formula has been created for demanding users – from gamers and overclockers to IT professionals who expect maximum stability and performance.

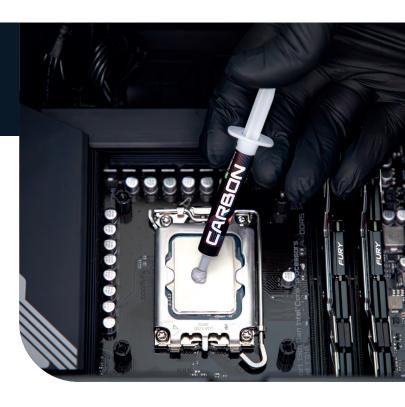
Product features:

- Ultra-high thermal conductivity: 15.2 W/mK,
- contains carbon nanoparticles,
- stability and reliability in long-term operation,
- versatile applications,
- easy application,
- RoHS compliant.

Applications:

- processors and GPUs requiring top-level cooling performance,
- gaming PCs and workstations,
- components that demand intensive and stable heat dissipation.





| Physicochemical properties | |
|--|---|
| Appearance | Gray paste |
| Density at 20°C | 2.64 g/cm ³ |
| Thermal conductivity | 15.2 W/mK |
| Operating temperature range | -20°C to 130°C |
| Thermal impedance | <0.0008 °C·in²/W |
| Evaporation | Does not evaporate |
| Viscosity | Does not flow |
| Thixotropic index | 280±10 |
| Volume resistivity (ASTM D257) | 9.7*10 ⁸ p, Ω x m 9.7*10 ¹⁰ Ω x cm |
| Dielectric loss factor tg δ (ASTM D150) | 0.30 (120 Hz) 0.078 (1 kHz) 0.012 (10 kHz) 0.002 (100 kHz) |
| Relative dielectric permeability $\epsilon_{_{\rm f}}$ (ASTM D150) | 42 (120 Hz) 35 (1 kHz) 34 (10 kHz) 32 (100 kHz) |
| Shelf life | 3 years |



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Compatibility:

Carbon Paste is compatible with a wide range of materials, such as aluminum, copper, and ceramics. Its formula prevents electrocorrosion, ensuring stability and safety even under extreme working conditions.

| Application method | |
|--------------------|-----|
| Syringe | Yes |
| Spatula | Yes |

Usage instructions:

Restricted to professional users. Read safety data sheet carefully prior to use.

Before use, make sure that the surfaces are clean and dry. Apply a small amount of thermal paste to the central point of the component surface and, using the included spatula, spread it evenly in a thin layer across the entire contact area. Then mount the heatsink, ensuring it is firmly pressed down to provide full contact and optimal heat transfer.

| Package | |
|---------|--|
| Syringe | 1 g (ART.AGT-324) - 5 pcs.* 3 g (ART.AGT-325) - 5 pcs.* |

^{*}Quantity of pcs. in a bulk package

Storage:

Store in a well-ventilated, cool, and dry place. Keep containers tightly closed when not in use. Protect from direct sunlight.

Technical support:

AG TermoPasty provides technical support, answering questions about the technical specifications and applications of our products. Please contact us via email at info@termopasty.pl.

Note:

The data presented in this document reflect our current state of knowledge and describe the typical properties and applications of the product. However, the responsibility for determining the suitability of this product for specific applications lies with the user. AG TermoPasty is not liable for the results of the product's use, as the conditions of its application are beyond our control.

